

Title (en)
DOUBLE SIDED RF CONNECTOR

Title (de)
DOPPELSEITIGER RF STECKVERBINDER

Title (fr)
CONNECTEUR HF DOUBLE FACE

Publication
EP 1084524 A1 20010321 (EN)

Application
EP 00913287 A 20000128

Priority
• US 0002279 W 20000128
• US 28337199 A 19990331

Abstract (en)
[origin: WO0059077A1] A connector which provides an interconnect between a pin and a flat conductor. The connector employs two bundles fabricated of densely packed gold plated wire for the electrical connection to the devices. The bundles are both housed in a dielectric sleeve structure and are themselves connected by a solid conductor. A portion of one wire bundle protrudes from one end of the sleeve structure to make electrical contact with a flat conductor in a mating assembly. The second wire bundle is recessed within the sleeve structure adjacent a second end of the sleeve structure. The pin is inserted into the second end in an installation, making electrical contact with the second wire bundle. The connector provides a robust electrical connection, and also provides for misalignment of the flat connector in addition to variations in the exact location of the pin. The length of the pin in the mating part can vary considerably, and the connector device still provides a controlled impedance interconnect over microwave frequencies. The connector can be installed in a larger assembly thus providing a large number of interconnections to be mating simultaneously. This is accomplished by providing clearances and tapers in the mating housing.

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H01R 13/658

IPC 8 full level
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